

October 2009

MOC70P1, MOC70P2, MOC70P3 Phototransistor Optical Interrupter Switch

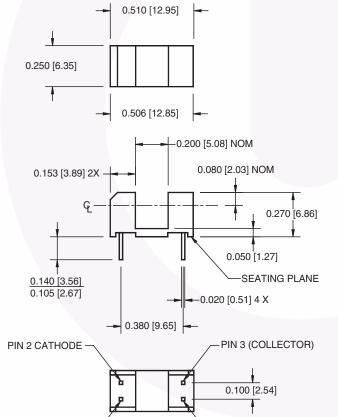
Features

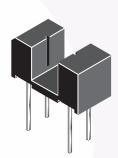
- No contact sensing
- 5mm gap
- .040" aperture
- Low profile
- PCB mount
- Transistor output

Description

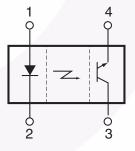
The MOC70PX consists of an infrared light emitting diode coupled to an NPN silicon phototransistor packaged into an injection molded housing. The housing is designed for wide gap, non contact sensing.

Package Dimensions





Schematic



Notes:

PIN 1 (ANODE)

- 1. Dimensions for all drawings are in inches (millimeters).
- 2. Tolerance of ± .010 (.25) on all non-nominal dimensions unless otherwise specified.

PIN 4 (EMITTER)

Absolute Maximum Ratings (TA = 25°C unless otherwise specified)

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Rating	Units	
T _{OPR}	Operating Temperature	-55 to +100	°C	
T _{STG}	Storage Temperature	-55 to +100	°C	
T _{SOL-I}	Soldering Temperature (Iron) ^(2,3,4,5)	240 for 5 sec	°C	
T _{SOL-F}	Soldering Temperature (Flow) ^(2,3,5)	260 for 10 sec	°C	
EMITTER				
I _F	Continuous Forward Current	50	mA	
V _R	Reverse Voltage	6	V	
P _D	Power Dissipation ⁽¹⁾	100	mW	
SENSOR				
V _{CEO}	Collector-Emitter Voltage	30	V	
V _{ECO}	Emitter-Collector Voltage	4.5	V	
I _C	Collector Current 20		mA	
P_{D}	Power Dissipation ⁽¹⁾ 150 mW			

Notes:

- 1. Derate power dissipation linearly, on each component, 1.33 mW/°C above 25°C.
- 2. RMA flux is recommended.
- 3. Methanol or isopropyl alcohols are recommended as cleaning agents.
- 4. Soldering iron tip 1/16" (1.6mm) from housing.
- 5. As long as leads are not under any stress or spring tension.

Electrical/Optical Characteristics (T_A = 25°C)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
EMITTER				'	•	
V _F	Forward Voltage	I _F = 50mA			1.8	V
I _R	Reverse Leakage Current	V _R = 6V			100	μΑ
SENSOR				•		
BV _{CEO}	Collector-Emitter Breakdown Voltage	$I_C = 10mA$	30			V
BV _{ECO}	Emitter-Collector Breakdown Voltage	I _E = 100μA	4			V
I _{CEO}	Collector-Emitter Leakage	V _{CE} = 10V, I _F = 0			100	nA
COUPLED						
I _{C(ON)}	Collector Current (See selection guide on the next page)					
V _{CE (SAT)}	Collector Emitter Saturation Voltage (See selection guide on the next page)					
t _(ON)	Turn-on Time	$I_F = 30 \text{mA}, V_{CC} = 5 \text{V}, R_L = 2.5 \text{k}\Omega$		20		μs
t _(OFF)	Turn-off Time	$I_F = 30 \text{mA}, V_{CC} = 5 \text{V}, R_L = 2.5 \text{k}\Omega$		80		μs

MOC70PX Optical Switch Selection Guide

Symbol	Device	Test Conditions	Min	Тур	Max	Units
ON-STATE CO	DLLECTOR CURR	ENT	•	•	•	•
I _{C(ON)}	MOC70P1	$I_F = 5mA, V_{CE} = 10V$	0.15			mA
	MOC70P2		0.30			mA
	MOC70P3		0.60			mA
	MOC70P1	$I_F = 20 \text{mA}, V_{CE} = 10 \text{V}$	1.0			mA
	MOC70P2		2.0			mA
	MOC70P3		4.0			mA
	MOC70P1	$I_F = 30 \text{mA}, V_{CE} = 10 \text{V}$	1.9			mA
	MOC70P2		3.0			mA
	MOC70P3		5.5			mA
COLLECTOR-	EMITTER SATUR	ATION VOLTAGE				1
V _{CE (SAT)}	MOC70P1	$I_C = 1.8 \text{mA}, I_F = 30 \text{mA}$			0.40	V
	MOC70P2	$I_C = 1.8 \text{mA}, I_F = 20 \text{mA}$			0.40	V
	MOC70P3				0.40	V

Typical Performance Characteristics

Fig. 1 Forward Current vs. Forward Voltage 55 50 IF - FORWARD CURRENT (mA) $T_A = 30^{\circ}C$ 45 40 T_A = 25°C 35 T_A = 70°C 30 25 20 15 10 0 0.2 0.4 0.6 1.4 1.6 1.8 V_F - FORWARD VOLTAGE (V)

Fig. 2 Forward Voltage vs. Ambient Temperature

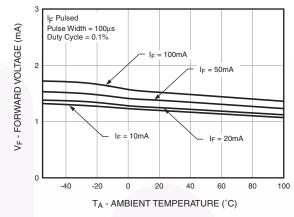


Fig. 3 Collector-Emitter Dark Current (Normalized) vs. Ambient Temperature

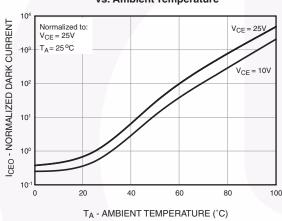


Fig. 4 Collector Current vs. Collector-Emitter Voltage

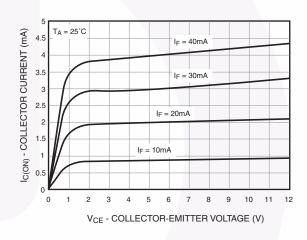


Fig. 5 Collector Current vs. Forward Current

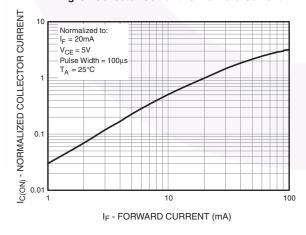
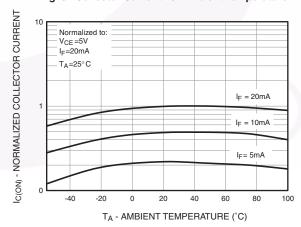
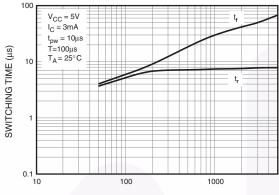


Fig. 6 Collector Current vs. Ambient Temperature



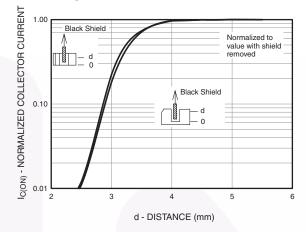
Typical Performance Characteristics (Continued)

Fig. 7 Switching Time Vs. Load Resistance



R_L - LOAD RESISTANCE (Ω)

Fig. 8 Collector Current Vs. Shield Distance







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